

3RB-6 Series

Description

GDT is placed in front of, and in parallel with, sensitive telecom equipment such as power lines, communication lines, signal lines and data transmission lines to help protect them from damage caused by transient surge voltages that may result from lightning strikes and equipment switching operations. These devices do not influence the signal in normal operation. However, in the event of an overvoltage surge, such as a lightning strike, the GDT switches to a low impedance state and diverts the energy away from the sensitive equipment.

Our GDT offer a high level of surge protection, a broad voltage range, low capacitance, and many form factors including new surface mount devices, which makes them suitable for applications such as Main Distribution Frame (MDF) modules, high data-rate telecom applications (e.g. ADSL, VDSL), and surge protection on power lines. Their low capacitance also results in less signal distortion. When used in a coordinated circuit protection solution with PolySwitch devices, they can help equipment manufacturers meet stringent safety regulatory standar



Electrical symbol

Applications

equipment

Data lines

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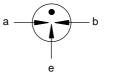
Communication

CATV equipment

Power supplies

Telecom SLIC protection

Broadband equipment



a = Tip b = Ring e = Ground (center electrode)

ADSL equipment,

including ADSL2+

XDSL equipment

Test equipment

equipment

Satellite and CATV

Consumer electronics

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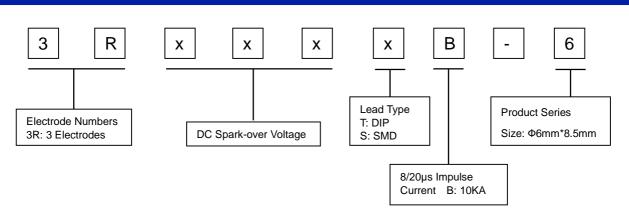
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Fea ures

- I Excellent response to fast rising transients
- I Stable breakdown voltage
- I GHz working frequency
- I 8/20µs Impulse current capability: 10KA
- I Non-Radioactive
- I Ultra Low capacitance (<1.5pF)
- I High insulation resistance
- I Lead-free and RoHS compliant
- I UL 497B Recognized: E465335
- I Size: Φ6mm*8.5mm
- I Storage and operational temperature: -40~+90°C

Part Number Code









3RB-6 Series

Electrical Characteristics

Part Number			DC Spark-over Voltage ^{1) 2)} @100V/S		ulse			Life Ratings			
				Spark-over Voltage ³⁾		Insulation Resistance	Capacitance @1MHz	Impulse Discharge Current		AC Discharge	Impulse Life
				100V/µS	S 1KV/μS	í í	e i i i i i	@8/20µs ⁵⁾		Current @50Hz 1S ⁵⁾	@10/1000µS 100A ⁵⁾
				Max	Max	Min	Мах	Nominal ±5 times	Max 1 time	Nominal 5 times	Min
DIP	SMD	DIP-F	v	v	v	GΩ	pF	KA	KA	Α	Times
3R070TB-6	3R070SB-6	3R070TB-6F	70±20%	500	600	1	1.5	10	15	10	300
3R075TB-6	3R075SB-6	3R075TB-6F	75±20%	500	600	1	1.5	10	15	10	300
3R090TB-6	3R090SB-6	3R090TB-6F	90±20%	500	600	1	1.5	10	15	10	300
3R150TB-6	3R150SB-6	3R150TB-6F	150±20%	500	600	1	1.5	10	15	10	300
3R230TB-6	3R230SB-6	3R230TB-6F	230±20%	500	700	1	1.5	10	15	10	300
3R250TB-6	3R250SB-6	3R250TB-6F	250±20%	500	700	1	1.5	10	15	10	300
3R300TB-6	3R300SB-6	3R300TB-6F	300±20%	700	900	1	1.5	10	15	10	300
3R350TB-6	3R350SB-6	3R350TB-6F	350±20%	700	900	1	1.5	10	15	10	300
3R400TB-6	3R400SB-6	3R400TB-6F	400±20%	800	1000	1	1.5	10	15	10	300
3R470TB-6	3R470SB-6	3R470TB-6F	470±20%	900	1100	1	1.5	10	15	10	300
3R600TB-6	3R600SB-6	3R600TB-6F	600±20%	1100	1300	1	1.5	10	15	10	300
Glow Voltage	at 10mA				~60\	1					
Arc Voltage a	t 1A				~10V	1					
Glow to Arc transition Current				~1A							
Operation and storage -4					-40~9	90°C					
Climatic category (IEC60068-1)						90/21					
Marking, Blac	k				RUIL xxx I xxx B X	3 X -Nominal volt	oulse Discharge	Current			
Weight					. ~1.2	ōg					
Surface treatment					DIP -Nickel Plated SMD -Matte-tin plated						

2)

In ionized mode 3) Tip or ring electrode to center electrode

4) Insulation Resistance Measuring Voltage:

70V, 75V at DC 25V 90V~150V at DC 50V

Other at DC 100V

⁵⁾ Total current through center electrode, half value through tip respectively ring electrode.

Terms in accordance with ITU-T Rec. K.12, IEC 61643-311, GB/T 9043.

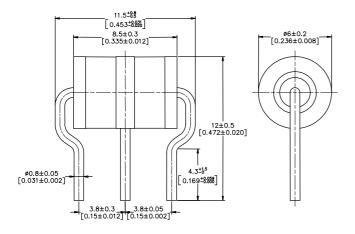


3RB-6 Series

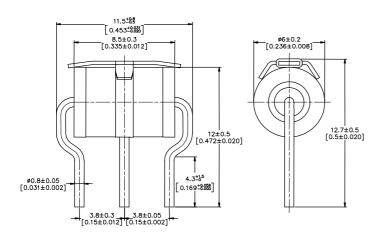
RoHS

Dimensions (Unit: mm/inch)

DIP Series (3RxxxTB-6)

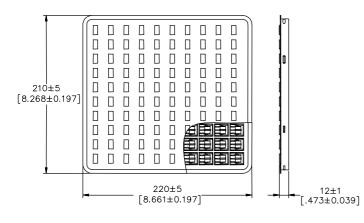


DIP Series (3RxxxTB-6F)

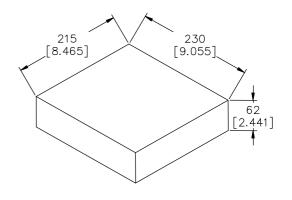


Packaging Information (Unit: mm/inch)

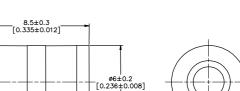
"DIP Series" and "DIP-F Series" Packaging (Bulk)



100PCS/ Plastic Tray



500PCS, 5 Plastic Trays / Inner Box

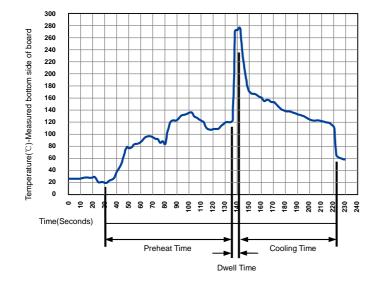


SMD Series (3RxxxSB-6)



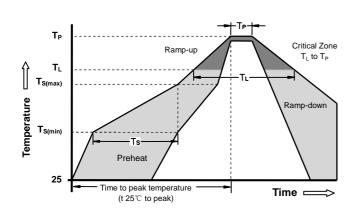
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Soldering Parameters - Wave soldering (Thru-Hole Devices)



Wave Sol	dering Condition	Pb-Free assembly			
	Temperature Min	100°C			
Preheat	Temperature Max	150°C			
	Time (Min to Max)	60-180 Seconds			
Solder Po	t Temperature	280°C Max			
Solder Dv	vell Time	2-5 Seconds			

Soldering Parameters - Reflow Soldering (Surface Mount Devices)



Reflow Co	ondition	Pb - Free assembly		
	-Temperature Min (T _{s(min)})	150°C		
Preheat	-Temperature Max (T _{s(max)})	200°C		
	- Time (min to max) (t_s)	60 -180 Seconds		
Average r T _L) to pea	amp up rate (Liquids Temp k	3°C/second max		
T _{S(max)} to T	⁻ L - Ramp-up Rate	5°C/second max		
Reflow	- Temperature (T∟) (Liquids)	217°C		
	- Time (min to max) (t_s)	60 -150 Seconds		
Peak Tem	perature (T _P)	260 +0/-5°C		
Time with Temperat	in 5°C of actual peak ure (t _p)	10 - 30 Seconds		
Ramp-dov	wn Rate	6°C/second max		
Time 25°C	C to peak Temperature (T _P)	8 minutes Max		
Do not ex	ceed	260°C		

